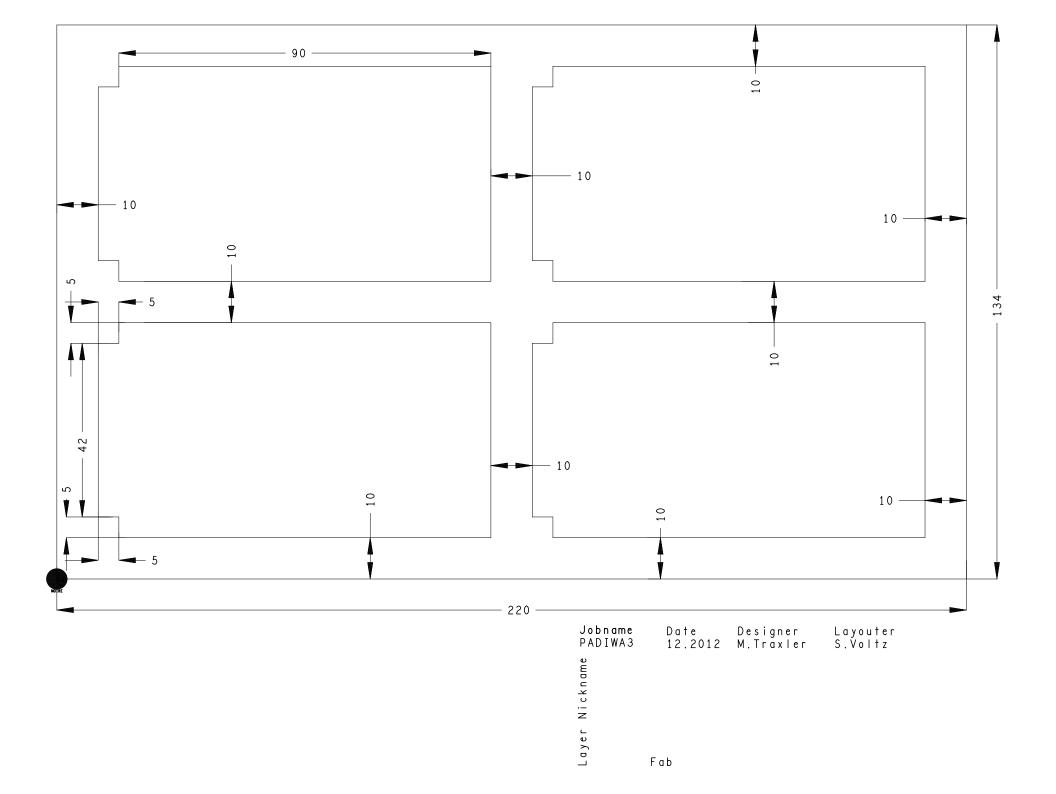
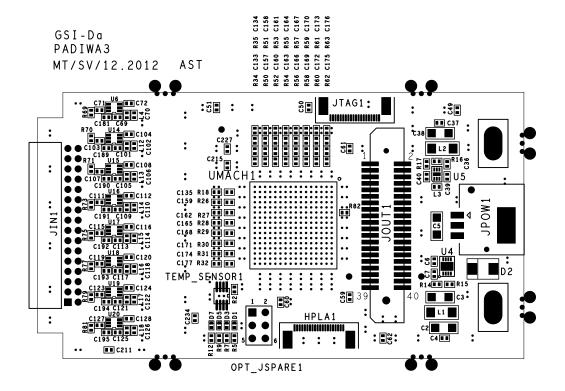


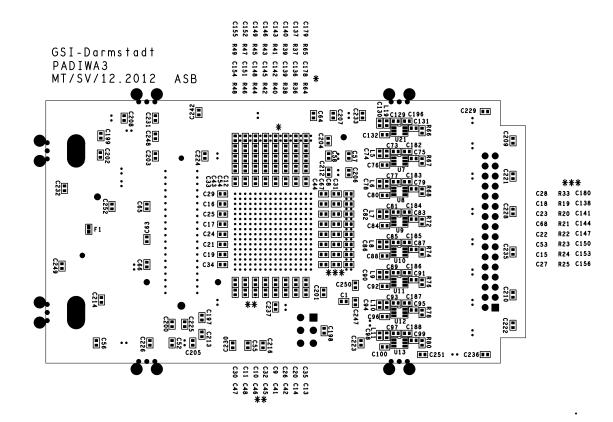
DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
ALL ONLYS AND IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
	0.2	PLATED	1008
•	0.4	PLATED	1
•	0.9	PLATED	32
0	1.0	PLATED	6
<b>®</b>	1.0	NON-PLATED	18
0	1.1	NON-PLATED	2
®	1.4	NON-PLATED	1
®	1 . 6	NON-PLATED	1
0	2.4	NON-PLATED	12
A	6.5x3.5	NON-PLATED	2

TOTAL HOLES: 1083

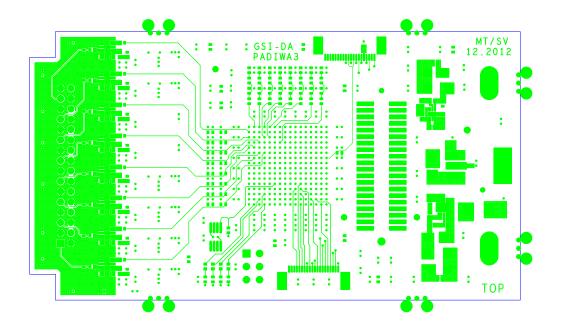
Jobname Date Designer Layouter PADIWA3 12.2012 M.Traxler S.Voltz



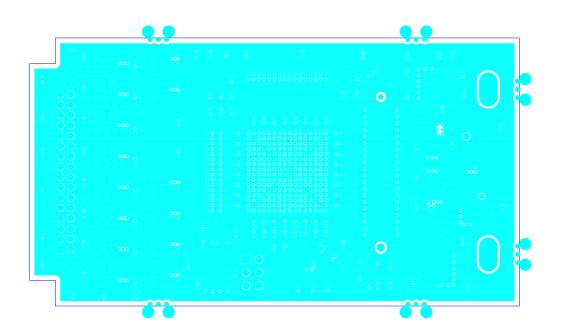




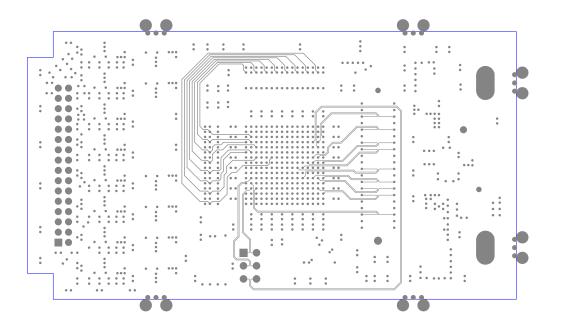
## Signals



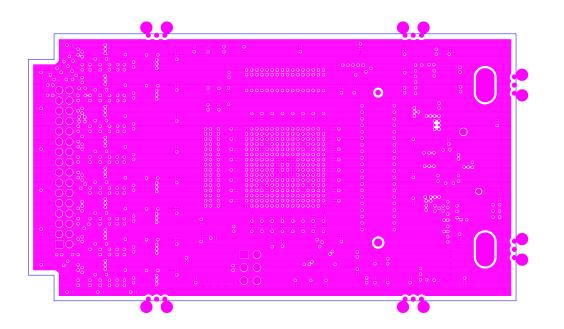
# GND-Plane



#### Diff.Pairs

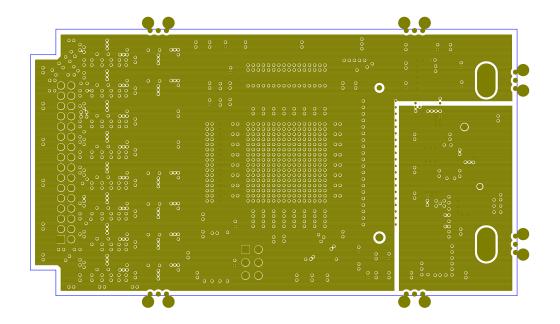


## VREG-Plane

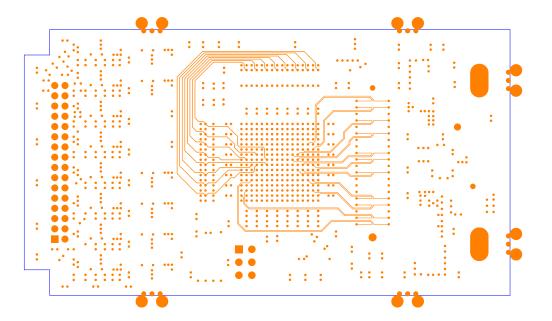




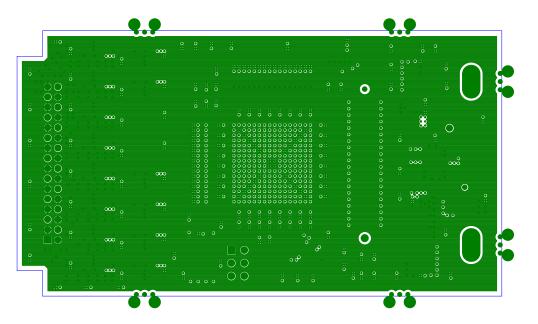
### VTERM-Plane, VIN-Plane

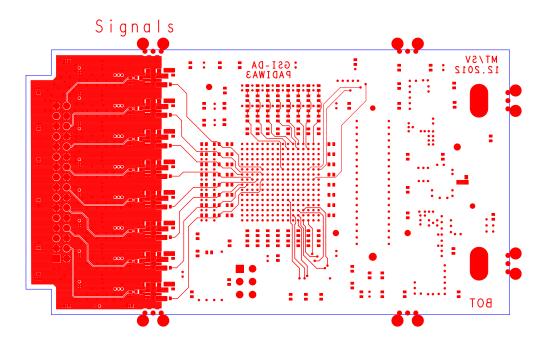


## Diff.Pairs



### GND-Plane





JobnameDateDesignerLayouterPADIWA312.2012M.TraxlerS.Voltz

Bot Bot

#### LAGENAUFBAU (Impedanz) 8 - Lagen Kern: mm Cu / μm WE-Artikel Nr.: 8 - Lagen WÜRTH ELEKTRONİK **GSI PADIWA2 KUNDE:** BASIS-PREPREG ANZAHL/TYP LAGENBEZEICHNUNG **AUFBAU** ENDDICKE CU Material **KUNDE** WE [µm] Folie 9 µm 1) 9 ====== 1x 2113 94 2 18 µm 18 150 0,15 mm 3 3 18 µm 18 ====== 2x 2116 214 4 18 µm 18 510 0,51 mm 5 5 18 µm 18 ====== 2x 2116 214 6 18 µm 18 0,15 mm 150 7 7 18 µm 18 ====== 1x 2113 94 Folie BOT/RS 9 µm 8 9

Imp

Zdiff

Zo

Imp.-Lage

LBBR ISO

L3/L6 = 100,10 Ohm 100µm 120µm

Zdiffcopl L3/L6 = 100,30 Ohm 100μm 130μm

**Zo copl** VS/RS =49,90 Ohm 130μm

VS/RS =49,30 Ohm 150 μm

KUNDEN-FORDERUNG

[µm]

	3 150 hf												
							Gesamtdicke Material:			1552			
							Anmerkung: Werte für Prepreg sind Mittelwerte (der genaue Wert ist von den Leiterbildstrukturen abhängig)						
MATERIALDICKE:			1,53	+/-	0,16	mm		Index	Datur	um: Bearbeiter:		arbeiter:	
DICKE über galv. Endoberfläche			1,60	+/-	0,17	mm					A.Wodke		
DICKE über LSM incl.galvKupfer			1,64	+/-	0,18	mm			05.12.2012				
Kundenforderung:				+/-		mm	Messstelle:						
Erstellt			Geprüft				Freigegeben	geben					
am	von		am		von			von		Revisi	Revision		
28.09.2006 M.Kress			24.10.2006 <b>S.Baumann</b>			ın	25.10.2006	R.Tauras (		00	Seite:	1+	

ISO z. Masse

1) Kupferenddicke Außenlagen nach IPC (35µm Forderung)

150µm

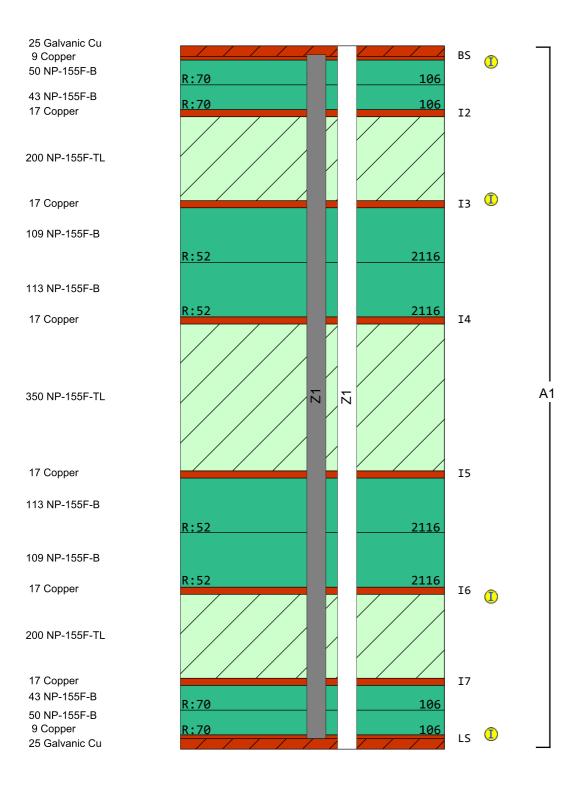
150µm



# Stack up 12444-0-0

(8M15NPI20I35K17)

Stack up File Material (µm) Assembly





# Impedanzen 12444-0-0

